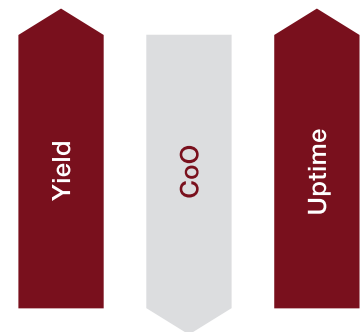




# Electro-Plated Diamond Wire

## Reduced cost of ownership | Higher throughput

- Faster cut times
  - 6 - 8 x faster than slurry, application dependent
  - Increased capacity with lower capital expenditures
  - Faster ROI to justify initial capital investment
- Roadmap to lower wafer cost and higher throughput
  - Lower cost resulting from reduced TCO
  - Less expensive secondary process costs
  - Re-use of wire
  - Reduced utilities
- Less plant complexity
  - Reduced running costs such as electricity and cooling water
  - Bundled consumables for optimized processing



## Higher throughput

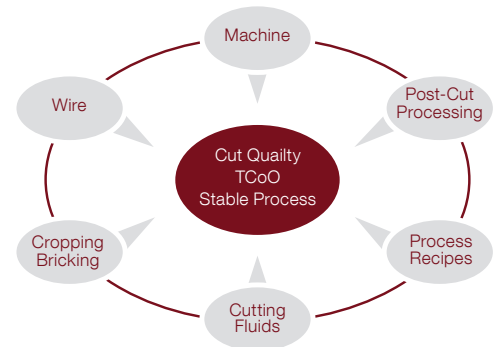
- Flatter wafers
  - Roadmap for thinner wafers
- Holistic approach to cutting
- Improved wafer topology
- Excellent cutting accuracy

## Maintenance and environment friendly

- Fewer wire spool changes
- Cleaner and faster process
- Ability to use water-based cutting fluids

## Seamless integration into existing waferline systems

- Innov Wire Technology offers you best-in-class consumables and product support services
- We can assist and support you with the introduction of water-based diamond slicing in your facility
- Through Innov Wire Technology expertise, we are able to offer a consumables package that allows for maximized performance, lower CoO, and increased yield and throughput



# Diamond Wire

## Electro-Plated Wire Portfolio

Application	Core Diameter (microns)	Diamond Size	Concentration	Outer Diameter (microns)
PV Wafering	70	6-12	High	83
		6-12	High	90
	80	8-16	High / Ultra	93 / 95
		8-16	Standard / Ultra	113 / 116
Sapphire & Alternate Material Wafering	100	10-20	High	124
		10-20	Standard / High	149
		12-25	Standard / High	156
	120	22-36	Standard / High	169
		10-20	Standard / High	167
		12-25	Standard / High	174
	140	22-36	Standard / High	187
		12-25	Standard / High	192
		22-36	Standard / High	212
	160	30-40	Standard	221
		40-50	Standard	225
		22-36	Standard / High	225
30-40		Standard / High	240	
175	40-50	Standard	256	
	22-36	Standard	241	
	30-40	Standard	257	
Bricking   Cropping	200	40-50	Standard	279
		22-36	Standard / High	338
		30-40	Standard	356
	300	40-60	Standard / High	378
		30-40	Standard / High / Ultra	396
		40-60	Standard / High	423
	350	30-40	Standard / High	441
		40-60	Standard / High	468
		30-40	Standard / High	441
400	40-60	Standard / High	468	

## Additional Consumable Offerings\*

### Cutting Fluids

- WaferKool 2010
- WaferKool 3010

### Saw Cleaners

- SawKleen

### Beams

- IWT 710 beam  
custom sizes available

### Anti-Foam

- SAG 2001

## Questions | Request for Quote

To facilitate your order, please provide the following information

#### Required information:

- Diamond wire
- Wire outer diameter or kerf
- Type of spool

#### Useful information, if known:

- Wire core diameter
- Wire speed
- Wire tension at slicing
- Diamond grit size
- Process time

### Point of Contact:

sales@innowwiretech.com  
www.innowwiretechnology.com

\*Detailed consumable product information can be provided upon request

Designed and manufactured by IWT  
Part of the Thermo Technologies Group